Texas Instruments

SN54HC74, SN74HC74

SCLS094E – DECEMBER 1982 – REVISED DECEMBER 2015

SNx4HC74 Dual D-Type Positive-Edge-Triggered Flip-Flops With Clear and Preset

1 Features

- Wide Operating Voltage Range: 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 40-µA Maximum I_{CC}
- Typical t_{pd} = 15 ns
- ±4-mA Output Drive at 5 V
- Very Low Input Current of 1 µA

2 Applications

- Ultrasound System
- Fans
- Lab Instrumentation
- Vacuum Cleaners
- Video Communications System
- IP Phone: Wired

3 Description

The SNx4HC74 devices contain two independent D-type positive-edge-triggered flip-flops. A low level at the preset ($\overline{PRE}$) or clear ($\overline{CLR}$) inputs sets or resets the outputs, regardless of the levels of the other inputs. When $\overline{PRE}$ and $\overline{CLR}$ are inactive (high), data at the data (D) input meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of CLK. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74HC74N	PDIP (14)	19.30 mm x 6.40 mm
SN74HC74NS	SO (14)	10.20 mm x 5.30 mm
SN74HC74D	SOIC (14)	8.70 mm x 3.90 mm
SN74HC74DB	SSOP (14)	6.50 mm x 5.30 mm
SN74HC74PW	TSSOP (14)	5.00 mm x 4.40 mm
SNJ54HC74J	CDIP (14)	21.30 mm x 7.60 mm
SNJ54HC74W	CFP (14)	9.20 mm x 6.29 mm
SNJ54HC74FK	LCCC (20)	8.90 mm x 8.90 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Logic Diagram (Positive Logic)

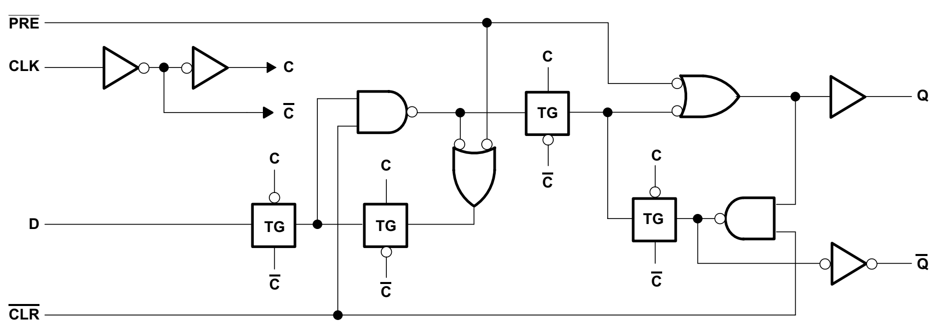


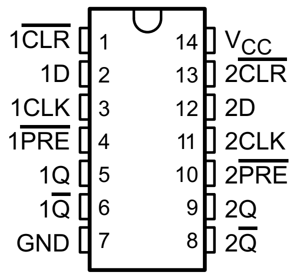
Table of Contents

4 Revision History

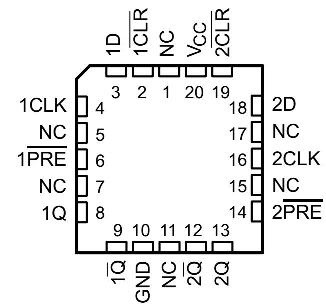
Changes from Revision D (July 2003) to Revision E	**Page**
• Added *Applications*, *Device Information* table, *Pin Functions* table, *ESD Ratings* table, *Thermal Information* table, *Typical Characteristics*, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section.	1

5 Pin Configuration and Functions

N, NS, D, DB, PW, J, or W Package
14-Pin PDIP, SO, SOIC, SSOP, TSSOP, CDIP, or CFP
Top View



FK Package
20-Pin LCCC
Top View



NC – No internal connection

Pin Functions

PIN			I/O	DESCRIPTION
NAME	LCCC	SOIC, SSOP, CDIP, PDIP, SO, TSSOP, CFP NO.		
1CLK	4	3	I	Clock input
$\overline{\text{1CLR}}$	2	1	I	Clear input - Pull low to set 1Q output low
1D	3	2	I	Input
$\overline{\text{1PRE}}$	6	4	I	Preset input
1Q	8	5	O	Output
$\overline{\text{1Q}}$	9	6	O	Inverted output
2CLK	16	11	I	Clock input
$\overline{\text{2CLR}}$	19	13	I	Clear input - Pull low to set 1Q output low
2D	18	12	I	Input
$\overline{\text{2PRE}}$	14	10	I	Preset input
2Q	13	9	O	Output
$\overline{\text{2Q}}$	12	8	O	Inverted output
GND	10	7	—	Ground
NC	1	—	—	No connect (no internal connection)
	5			
	7			
	11			
	15			
	17			
V_{CC}	20	14	—	Supply

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
I_{IK}	Input clamp current(2)	$V_I < 0$ or $V_I > V_{CC}$		±20	mA
I_{OK}	Output clamp current(2)	$V_O < 0$ or $V_O > V_{CC}$		±20	mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}		±25	mA
	Continuous current through V_{CC} or GND			±50	mA
T_j	Junction temperature range			150	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions.

6.3 Recommended Operating Conditions

See (1)

			SN54HC74			SN74HC74			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		2	5	6	2	5	6	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5			1.5			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 6 V	4.2			4.2			
V_{IL}	Low-level input voltage	V_{CC} = 2 V			0.5			0.5	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 6 V			1.8			1.8	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
$\Delta t/\Delta v$	Input transition rise and fall time	V_{CC} = 2 V			1000			1000	ns
		V_{CC} = 4.5 V			500			500	
		V_{CC} = 6 V			400			400	
T_A	Operating free-air temperature		–55		125	–40		85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, SCBA004.

6.4 Thermal Information

THERMAL METRIC[(1)]		SN74HC74 D (SOIC)	SN74HC74 DB (SSOP)	SN74HC74 N (PDIP)	SN74HC74 NS (SO)	SN74HC74 PW (TSSOP)	SN54HC74 J (CDIP)	SN54HC74 W (CFP)	SN54HC74 FK (LCCC)	UNIT
		14 PINS					14 PINS		20 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	86	96	80	76	113	—	—	—	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	—	—	—	—	—	15.05	14.65	5.61	

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

6.5 Electrical Characteristics

over recommended operating free-air temperature range, T_A = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS			V_{CC}	MIN	TYP	MAX	UNIT
V_{OH}	$V_I = V_{IH}$ or V_{IL}	I_{OH} = –20 µA		2 V	1.9	1.998		V
				4.5 V	4.4	4.499		
				6 V	5.9	5.999		
		I_{OH} = –4 mA	T_A = 25°C	4.5 V	3.98	4.3		
			SN54HC74		3.7			
			SN74HC74		3.84			
		I_{OH} = –5.2 mA	T_A = 25°C	6 V	5.48	5.8		
			SN54HC74		5.2			
			SN74HC74		5.34			
V_{OL}	$V_I = V_{IH}$ or V_{IL}	I_{OL} = 20 µA		2 V		0.002	0.1	V
				4.5 V		0.001	0.1	
				6 V		0.001	0.1	
		I_{OL} = 4 mA	T_A = 25°C	4.5 V		0.17	0.26	
			SN54HC74				0.4	
			SN74HC74				0.33	
		I_{OL} = 5.2 mA	T_A = 25°C	6 V		0.15	0.26	
			SN54HC74				0.4	
			SN74HC74				0.33	
I_I	$V_I = V_{CC}$ or 0		T_A = 25°C	6 V		±0.1	±100	nA
			SN54HC74, SN74HC74				±1000	
I_{CC}	$V_I = V_{CC}$ or 0,	I_O = 0	T_A = 25°C	6 V			4	µA
			SN54HC74				80	
			SN74HC74				40	
C_i				2 V to 6 V		3	10	pF
C_{pd}	No load			2 V to 6 V		35		pF

6.6 Timing Requirements

over recommended operating free-air temperature range, T_A = 25°C (unless otherwise noted)

			V_{CC}	T_A	MIN	MAX	UNIT
f_{clock}	Clock frequency		2 V	T_A = 25°C		6	MHz
				SN54HC74		4.2	
				SN74HC74		5	
			4.5 V	T_A = 25°C		31	
				SN54HC74		21	
				SN74HC74		25	
			6 V	T_A = 25°C	0	36	
				SN54HC74	0	25	
				SN74HC74	0	29	
t_w	Pulse duration	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	2 V	T_A = 25°C	100		ns
				SN54HC74	150		
				SN74HC74	125		
			4.5 V	T_A = 25°C	20		
				SN54HC74	30		
				SN74HC74	25		
			6 V	T_A = 25°C	14		
				SN54HC74	25		
				SN74HC74	21		
		CLK high or low	2 V	T_A = 25°C	80		
				SN54HC74	120		
				SN74HC74	100		
			4.5 V	T_A = 25°C	16		
				SN54HC74	24		
				SN74HC74	20		
			6 V	T_A = 25°C	14		
				SN54HC74	20		
				SN74HC74	17		
t_{su}	Setup time before CLK↑	Data	2 V	T_A = 25°C	100		ns
				SN54HC74	150		
				SN74HC74	125		
			4.5 V	T_A = 25°C	20		
				SN54HC74	30		
				SN74HC74	25		
			6 V	T_A = 25°C	17		
				SN54HC74	25		
				SN74HC74	21		
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	2 V	T_A = 25°C	25		
				SN54HC74	40		
				SN74HC74	30		
			4.5 V	T_A = 25°C	5		
				SN54HC74	8		
				SN74HC74	6		
			6 V	T_A = 25°C	4		
				SN54HC74	7		
				SN74HC74	5		

Timing Requirements (continued)

over recommended operating free-air temperature range, T_A = 25°C (unless otherwise noted)

		V_{CC}	T_A	MIN	MAX	UNIT
t_h	Hold time, data after CLK↑	2 V		0		ns
		4.5 V		0		
		6 V		0		

6.7 Switching Characteristics

over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A	MIN	TYP	MAX	UNIT
f_{max}			2 V	T_A = 25°C	6	10		MHz
				SN54HC74	4.2			
				SN74HC74	6			
			4.5 V	T_A = 25°C	31	50		
				SN54HC74	21			
				SN74HC74	25			
			6 V	T_A = 25°C	36	60		
				SN54HC74	25			
				SN74HC74	29			
t_{pd}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	2 V	T_A = 25°C		70	230	ns
				SN54HC74			345	
				SN74HC74			290	
			4.5 V	T_A = 25°C		20	46	
				SN54HC74			69	
				SN74HC74			58	
			6 V	T_A = 25°C		15	39	
				SN54HC74			59	
				SN74HC74			49	
	CLK	Q or $\overline{Q}$	2 V	T_A = 25°C		70	175	
				SN54HC74			250	
				SN74HC74			220	
			4.5 V	T_A = 25°C		20	35	
				SN54HC74			50	
				SN74HC74			44	
			6 V	T_A = 25°C		15	30	
				SN54HC74			42	
				SN74HC74			37	
t_t		Q or $\overline{Q}$	2 V	T_A = 25°C		28	75	ns
				SN54HC74			110	
				SN74HC74			95	
			4.5 V	T_A = 25°C		8	15	
				SN54HC74			22	
				SN74HC74			19	
			6 V	T_A = 25°C		6	13	
				SN54HC74			19	
				SN74HC74			16	

6.8 Typical Characteristics

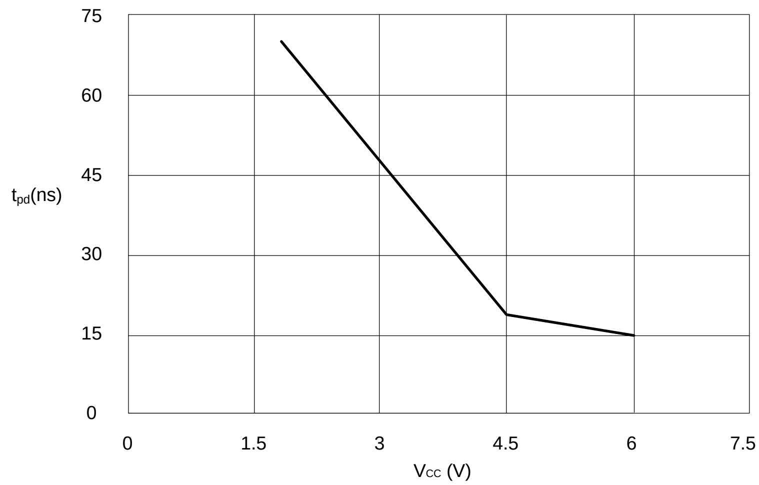
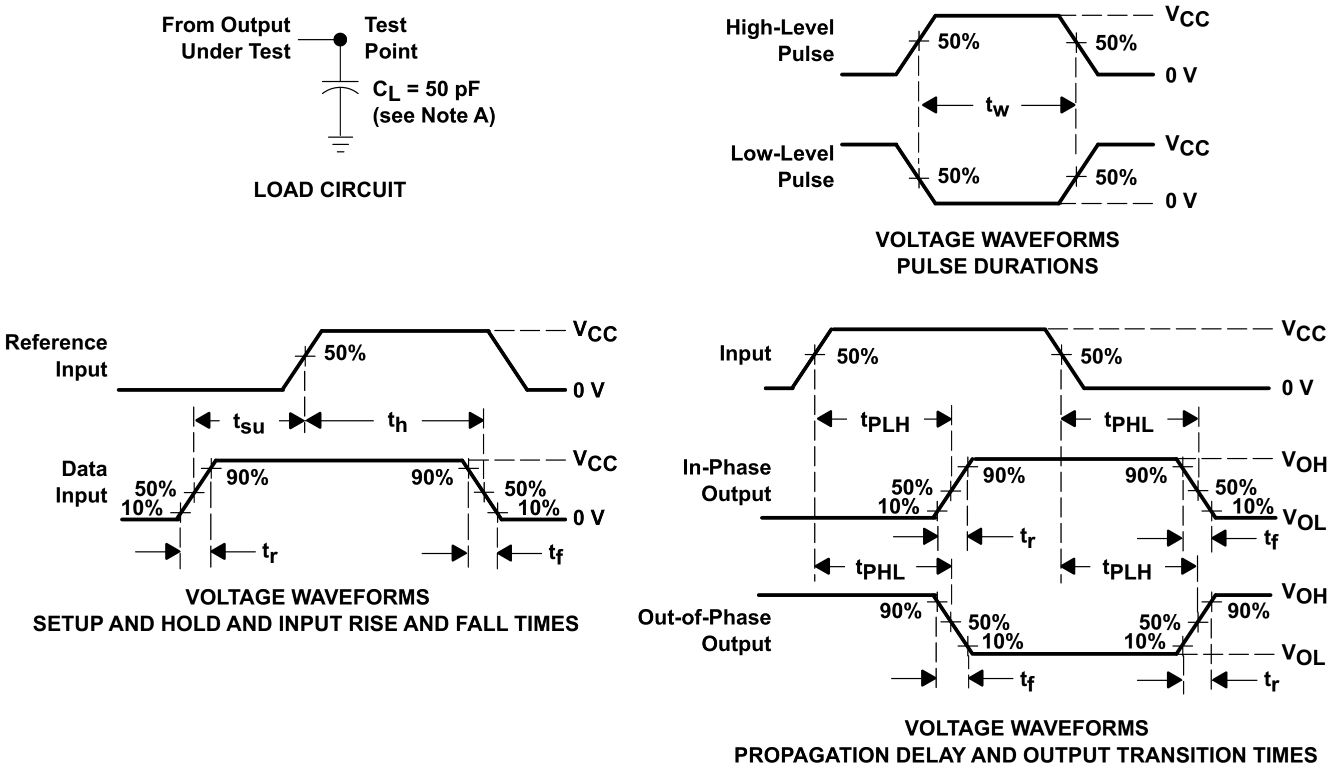


Figure 1. Typical Propagation Delay - CLK to Q

7 Parameter Measurement Information



A. C_L includes probe and test-fixture capacitance.

B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.

C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.

D. The outputs are measured one at a time with one input transition per measurement.

E. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 2. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

Figure 3 describes the SNx4HC74 devices. As the SNx4HC74 is a dual D-Type positive-edge-triggered flip-flop with clear and preset, the diagram below describes one of the two device flip-flops.

8.2 Functional Block Diagram

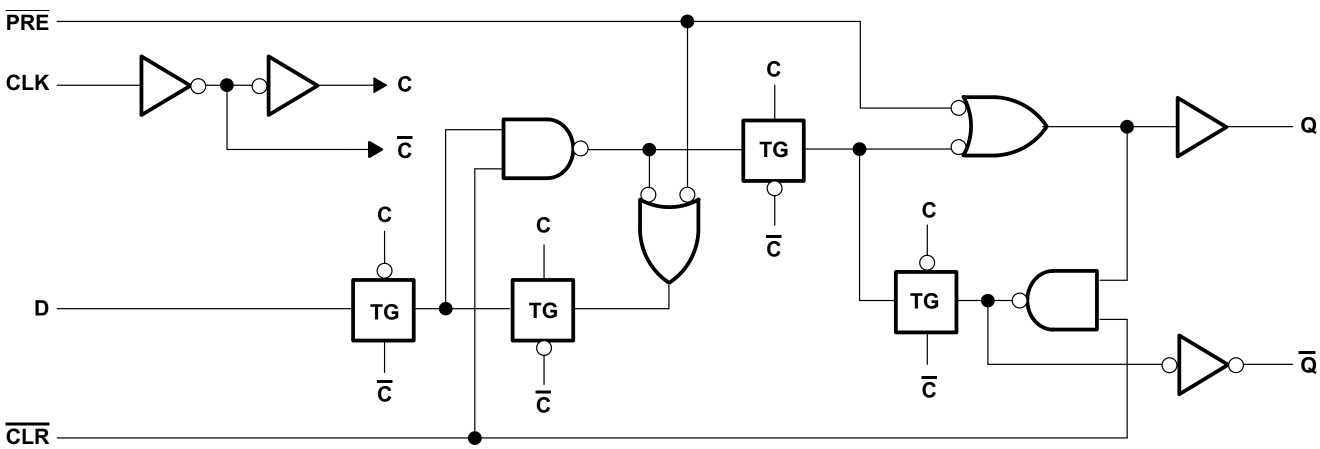


Figure 3. Logic Diagram (Positive Logic)

8.3 Feature Description

The SNx4HC74 inputs accept voltage levels up to 5.5 V. Refer to the *Recommended Operating Conditions* for appropriate input high and low logic levels.

8.4 Device Functional Modes

Table 1 lists the functional modes of the SNx4HC74.

Table 1. Function Table

INPUTS				OUTPUTS	
$\overline{\text{PRE}}$	$\overline{\text{CLR}}$	CLK	D	Q	$\overline{\text{Q}}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H(1)	H(1)
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q_0	$\overline{Q}_0$

(1) This configuration is nonstable; that is, it does not persist when $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ returns to its inactive (high) level.

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

A low level at the preset ($\overline{\text{PRE}}$) or clear ($\overline{\text{CLR}}$) input sets or resets the outputs, regardless of the levels of the other inputs. When $\overline{\text{PRE}}$ and $\overline{\text{CLR}}$ are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

The resistor and capacitor at the $\overline{\text{CLR}}$ pin are optional. If they are not used, the $\overline{\text{CLR}}$ pin should be connected directly to V_{CC} to be inactive.

9.2 Typical Application

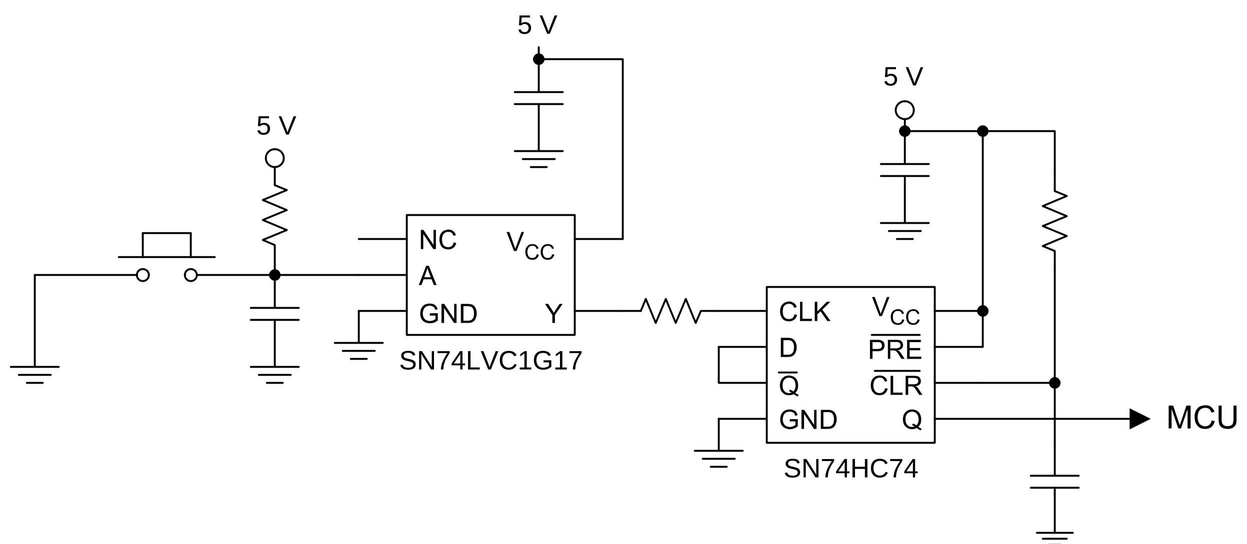


Figure 4. Device Power Button Circuit

9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. Outputs may be combined to produce higher drive, but the high drive will also create faster edges into light loads. Because of this, routing and load conditions should be considered to prevent ringing.

9.2.2 Detailed Design Procedure

1. Recommended Input Conditions:
   – For rise time and fall time specifications, see ($\Delta t/\Delta V$) in *Recommended Operating Conditions* table.
   – For specified high and low levels, see (V_{IH} and V_{IL}) in *Recommended Operating Conditions* table.
   – Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC}.
2. Recommended Output Conditions:
   – Load currents should not exceed 25 mA per output and 50 mA total for the part.
   – Series resistors on the output may be used if the user desires to slow the output edge signal or limit the output current.

Typical Application (continued)

9.2.3 Application Curve

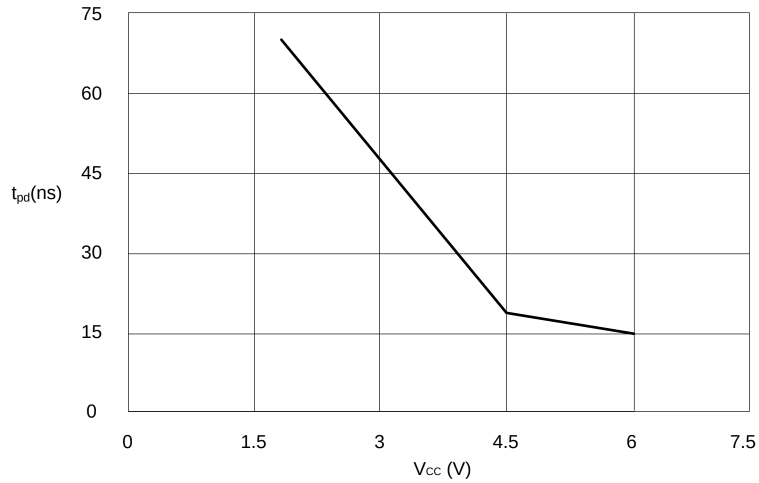


Figure 5. Typical Propagation Delay - $\overline{\text{CLR}}$ to Q

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions* table. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1-μF capacitor is recommended and if there are multiple V_{CC} terminals then .01-μF or .022-μF capacitors are recommended for each power terminal. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1-μF and 1-μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

11 Layout

11.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in Figure 6 are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally they are tied to GND or V_{CC}, whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it disables the output section of the part when asserted. This pin keeps the input section of the I/Os from being disabled and floated.

11.2 Layout Example

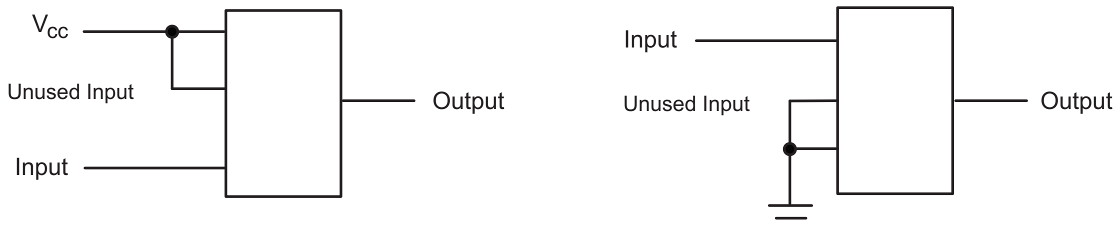


Figure 6. Layout Diagram

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation, see the following:

Implications of Slow or Floating CMOS Inputs, SCBA004

12.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54HC74	Click here	Click here	Click here	Click here	Click here
SN74HC74	Click here	Click here	Click here	Click here	Click here

12.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.4 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

12.5 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.